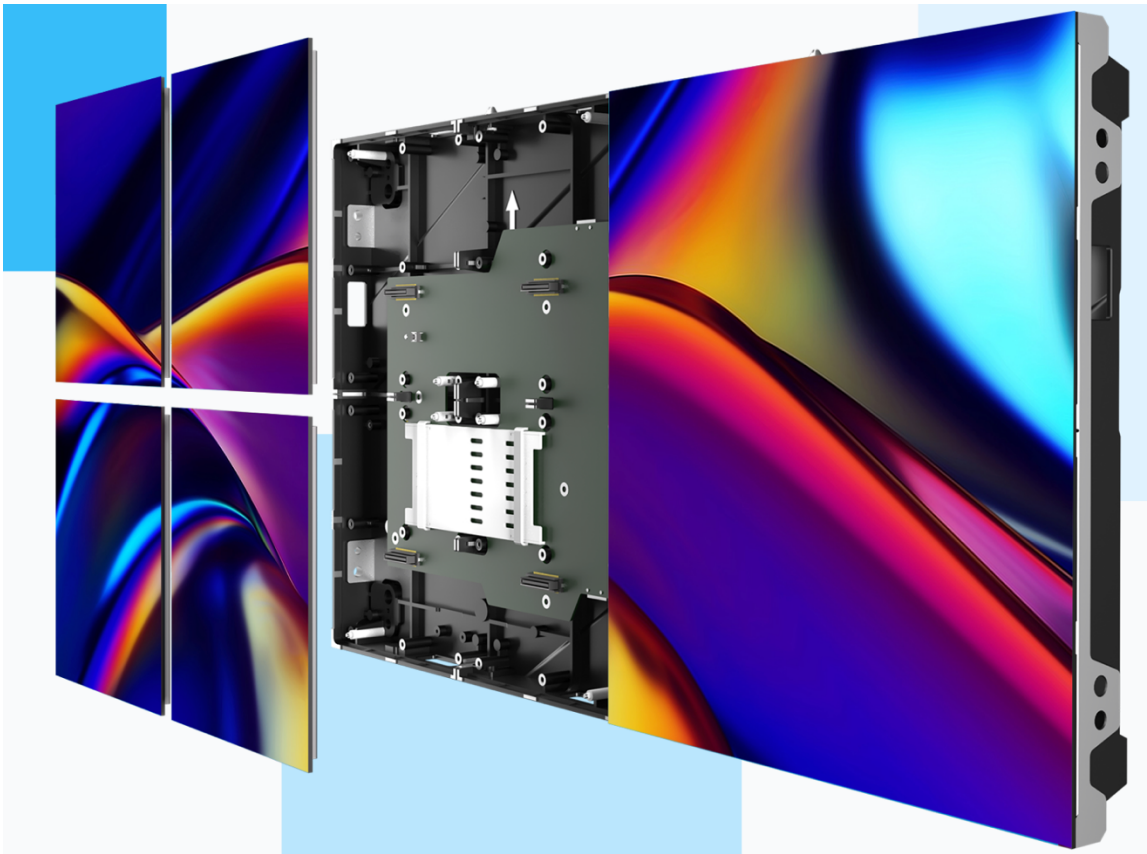

PRODUCT SPECIFICATION

XF 1.8 COB Flip Chip TECHNICAL SPECIFICATION	
Product series	XF
LED type	SMD 0306
Pixel Pitch (Width)	1.8750
Pixel Pitch (Height)	1.8750
Module resolution (W/Pixel)	160
Module resolution (H/Pixel)	90
Cabinet resolution (W/Pixel)	320
Cabinet resolution (H/Pixel)	180

Pixel density (pixels/m2)	284444
Module Dimension Width (mm)	300.00
Module Dimension Height (mm)	168.75
Cabinet Dimension Width (mm)	600.00
Cabinet Dimension Height (mm)	337.50
Panel material	Die-Cast
Cabinet area (m2)	0.20
Module weight (kg)	0.20
Cabinet weight (kg)	4.00
Color processing (bit)	13
Scan type	Vertical
Refresh Rate (Hz)	3840
Brightness （nit）	600
Heat Dissipation per m2 at Max Brightness (BTU/m2/h)	1245.380
Optimal Horizontal Viewing Angle （°）	170
Optimal Vertical Viewing Angle （°）	170
AC Input Voltage （V）	100...240
AC Input Frequency （Hz）	50...60
Power Consumption Typical （W/m2）	182
Power Consumption Maximum （W/m2）	365
Storage Temperature (°C)	−40°C~+60°C
Working Temperature (°C)	−20°C~+60°C
IP rating (Front/Rear)	40
Storage Humidity (RH)	10~60%RH
Working Humidity (RH)	10~90%RH
Lifetime Typical Value （hrs）	100000
Cabinet installation type	Fix
Cabinet installation shape	Flat

Maintenance	Front
Condition	Indoor
Certification	CE
No. of receiving cards (per cabinet)	1
Protective coating	Yes